

**MICROCHIP****24AA128/24LC128/24FC128****128K I²C™ CMOS Serial EEPROM****Device Selection Table**

Part Number	Vcc Range	Max. Clock Frequency	Temp. Ranges
24AA128	1.7-5.5V	400 kHz ⁽¹⁾	I
24LC128	2.5-5.5V	400 kHz	I, E
24FC128	1.7-5.5V	1 MHz ⁽²⁾	I

Note 1: 100 kHz for Vcc < 2.5V.**Note 2:** 400 kHz for Vcc < 2.5V.**Features:**

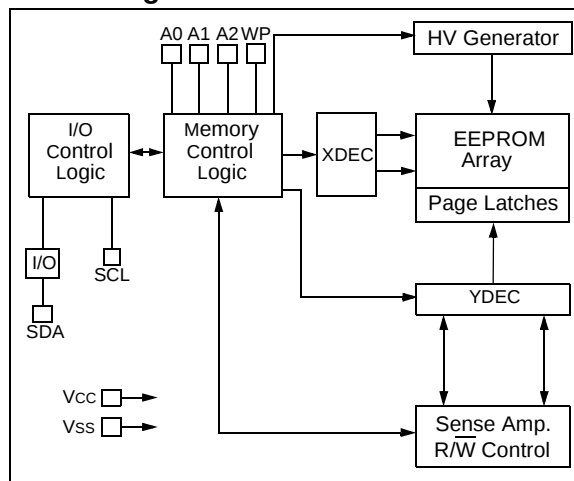
- Single supply with operation down to 1.7V for 24AA128/24FC128 devices, 2.5V for 24LC128 devices
- Low-Power CMOS Technology:
 - Write current 3 mA, typical
 - Standby current 100 nA, typical
- 2-Wire Serial Interface, I²C™ Compatible
- Cascadable up to Eight Devices
- Schmitt Trigger Inputs for Noise Suppression
- Output Slope Control to Eliminate Ground Bounce
- 100 kHz and 400 kHz Clock Compatibility
- 1 MHz Clock for FC Versions
- Page Write Time 5 ms, typical
- Self-Timed Erase/Write Cycle
- 64-Byte Page Write Buffer <adjust per device>
- Hardware Write-Protect
- ESD Protection >4000V
- More than 1 Million Erase/Write Cycles
- Data Retention > 200 years
- Factory Programming Available
- Packages include 8-lead PDIP, SOIC, TSSOP, DFN, MSOP, and Chip Scale Packages
- Pb-free and RoHS Compliant

• Temperature ranges:

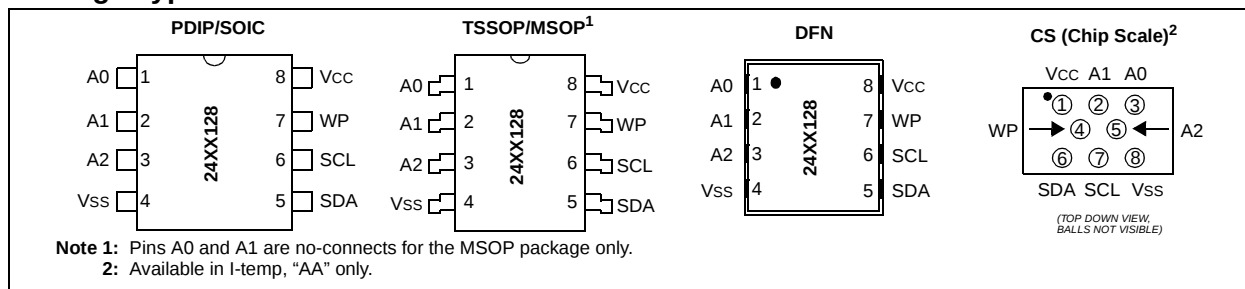
- Industrial (I): -40°C to +85°C
- Automotive (E): -40°C to +125°C

Description:

The Microchip Technology Inc. 24AA128/24LC128/24FC128 (24XX128*) is a 16K x 8 (128 Kbit) Serial Electrically Erasable PROM (EEPROM), capable of operation across a broad voltage range (1.7V to 5.5V). It has been developed for advanced, low-power applications such as personal communications or data acquisition. This device also has a page write capability of up to 64 bytes of data. This device is capable of both random and sequential reads up to the 128K boundary. Functional address lines allow up to eight devices on the same bus, for up to 1 Mbit address space. This device is available in the standard 8-pin plastic DIP, SOIC (3.90 mm and 5.28 mm), TSSOP, MSOP, DFN, and Chip Scale packages.

Block Diagram

*24XX128 is used in this document as a generic part number for the 24AA128/24LC128/24FC128 devices.

Package Types

24AA128/24LC128/24FC128

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings^(†)

V _{CC}	6.5V
All inputs and outputs w.r.t. V _{SS}	-0.6V to V _{CC} +1.0V
Storage temperature	-65°C to +150°C
Ambient temperature with power applied	-40°C to +125°C
ESD protection on all pins	≥ 4 kV

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: DC CHARACTERISTICS

DC CHARACTERISTICS			Electrical Characteristics:			
			Industrial (I): V _{CC} = +1.7V to 5.5V T _A = -40°C to +85°C			
			Automotive (E): V _{CC} = +2.5V to 5.5V T _A = -40°C to 125°C			
Param. No.	Sym.	Characteristic	Min.	Max.	Units	Conditions
D1	—	A0, A1, A2, SCL, SDA and WP pins:	—	—	—	—
D2	V _{IH}	High-level input voltage	0.7 V _{CC}	—	V	—
D3	V _{IL}	Low-level input voltage	—	0.3 V _{CC} 0.2 V _{CC}	V V	V _{CC} ≥ 2.5V V _{CC} < 2.5V
D4	V _{HYS}	Hysteresis of Schmitt Trigger inputs (SDA, SCL pins)	0.05 V _{CC}	—	V	V _{CC} ≥ 2.5V (Note 1)
D5	V _{OL}	Low-level output voltage	—	0.40	V	I _{OL} = 3.0 mA @ V _{CC} = 4.5V I _{OL} = 2.1 mA @ V _{CC} = 2.5V
D6	I _{LI}	Input leakage current	—	±1	μA	V _{IN} = V _{SS} or V _{CC} , WP = V _{SS} V _{IN} = V _{SS} or V _{CC} , WP = V _{CC}
D7	I _{LO}	Output leakage current	—	±1	μA	V _{OUT} = V _{SS} or V _{CC}
D8	C _{IN} , C _{OUT}	Pin capacitance (all inputs/outputs)	—	10	pF	V _{CC} = 5.0V (Note 1) T _A = 25°C, F _{CLK} = 1 MHz
D9	I _{CC} Read	Operating current	—	400	μA	V _{CC} = 5.5V, SCL = 400 kHz
	I _{CC} Write		—	3	mA	V _{CC} = 5.5V
D10	I _{CCS}	Standby current	—	1	μA	T _A = -40°C to +85°C SCL = SDA = V _{CC} = 5.5V A0, A1, A2, WP = V _{SS}
			—	5	μA	T _A = -40°C to 125°C SCL = SDA = V _{CC} = 5.5V A0, A1, A2, WP = V _{SS}

Note 1: This parameter is periodically sampled and not 100% tested.

24AA128/24LC128/24FC128

TABLE 1-2: AC CHARACTERISTICS

AC CHARACTERISTICS			Electrical Characteristics:			
			Industrial (I): V _{CC} = +1.7V to 5.5V TA = -40°C to +85°C			
			Automotive (E): V _{CC} = +2.5V to 5.5V TA = -40°C to 125°C			
Param. No.	Sym.	Characteristic	Min.	Max.	Units	Conditions
1	FCLK	Clock frequency	— — — —	100 400 400 1000	kHz	1.7V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.7V ≤ V _{CC} < 2.5V 24FC128 2.5V ≤ V _{CC} ≤ 5.5V 24FC128
2	THIGH	Clock high time	4000 600 600 500	— — — —	ns	1.7V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.7V ≤ V _{CC} < 2.5V 24FC128 2.5V ≤ V _{CC} ≤ 5.5V 24FC128
3	TLOW	Clock low time	4700 1300 1300 500	— — — —	ns	1.7V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.7V ≤ V _{CC} < 2.5V 24FC128 2.5V ≤ V _{CC} ≤ 5.5V 24FC128
4	TR	SDA and SCL rise time (Note 1)	— — —	1000 300 300	ns	1.7V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.7V ≤ V _{CC} ≤ 5.5V 24FC128
5	TF	SDA and SCL fall time (Note 1)	— —	300 100	ns	All except, 24FC128 1.7V ≤ V _{CC} ≤ 5.5V 24FC128
6	THD:STA	Start condition hold time	4000 600 600 250	— — — —	ns	1.7V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.7V ≤ V _{CC} < 2.5V 24FC128 2.5V ≤ V _{CC} ≤ 5.5V 24FC128
7	TSU:STA	Start condition setup time	4700 600 600 250	— — — —	ns	1.7V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.7V ≤ V _{CC} < 2.5V 24FC128 2.5V ≤ V _{CC} ≤ 5.5V 24FC128
8	THD:DAT	Data input hold time	0	—	ns	(Note 2)
9	TSU:DAT	Data input setup time	250 100 100	— — —	ns	1.7V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.7V ≤ V _{CC} ≤ 5.5V 24FC128
10	TSU:STO	Stop condition setup time	4000 600 600 250	— — — —	ns	1.7 V ≤ V _{CC} < 2.5V 2.5 V ≤ V _{CC} ≤ 5.5V 1.7V ≤ V _{CC} < 2.5V 24FC128 2.5 V ≤ V _{CC} ≤ 5.5V 24FC128
11	TSU:WP	WP setup time	4000 600 600	— — —	ns	1.7V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.7V ≤ V _{CC} ≤ 5.5V 24FC128
12	THD:WP	WP hold time	4700 1300 1300	— — —	ns	1.7V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.7V ≤ V _{CC} ≤ 5.5V 24FC128

Note 1: Not 100% tested. CB = total capacitance of one bus line in pF.

2: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

3: The combined TSP and VHYS specifications are due to new Schmitt Trigger inputs, which provide improved noise spike suppression. This eliminates the need for a TI specification for standard operation.

4: This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model, which can be obtained from Microchip's web site at www.microchip.com.

24AA128/24LC128/24FC128

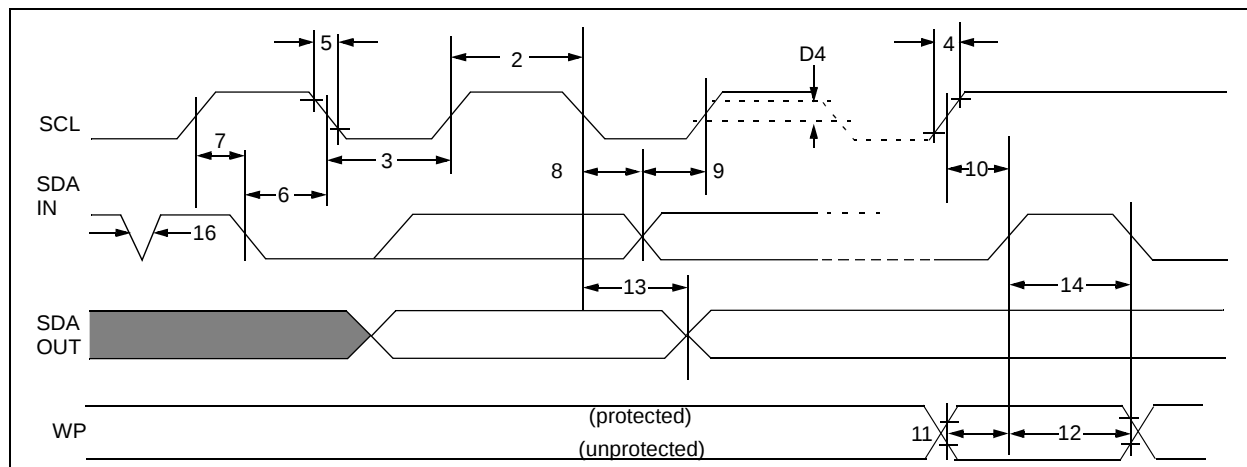
TABLE 1-2: AC CHARACTERISTICS (CONTINUED)

AC CHARACTERISTICS			Electrical Characteristics:			
			Industrial (I): $V_{CC} = +1.7V$ to $5.5V$ $T_A = -40^{\circ}C$ to $+85^{\circ}C$			
			Automotive (E): $V_{CC} = +2.5V$ to $5.5V$ $T_A = -40^{\circ}C$ to $125^{\circ}C$			
Param. No.	Sym.	Characteristic	Min.	Max.	Units	Conditions
13	TAA	Output valid from clock (Note 2)	— — — —	3500 900 900 400	ns	$1.7V \leq V_{CC} < 2.5V$ $2.5V \leq V_{CC} \leq 5.5V$ $1.7V \leq V_{CC} < 2.5V$ 24FC128 $2.5V \leq V_{CC} \leq 5.5V$ 24FC128
14	TBUF	Bus free time: Time the bus must be free before a new transmission can start	4700 1300 1300 500	— — — —	ns	$1.7V \leq V_{CC} < 2.5V$ $2.5V \leq V_{CC} \leq 5.5V$ $1.7V \leq V_{CC} < 2.5V$ 24FC128 $2.5V \leq V_{CC} \leq 5.5V$ 24FC128
15	TOF	Output fall time from V_{IH} minimum to V_{IL} maximum $C_B \leq 100$ pF	$10 + 0.1C_B$	250 250	ns	All except, 24FC128 (Note 1) 24FC128 (Note 1)
16	TSP	Input filter spike suppression (SDA and SCL pins)	—	50	ns	All except, 24FC128 (Notes 1 and 3)
17	TWC	Write cycle time (byte or page)	—	5	ms	—
18	—	Endurance	1,000,000	—	cycles	$25^{\circ}C$ (Note 4)

Note 1: Not 100% tested. C_B = total capacitance of one bus line in pF.

- 2:** As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.
- 3:** The combined TSP and V_{HYS} specifications are due to new Schmitt Trigger inputs, which provide improved noise spike suppression. This eliminates the need for a TI specification for standard operation.
- 4:** This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model, which can be obtained from Microchip's web site at www.microchip.com.

FIGURE 1-1: BUS TIMING DATA



24AA128/24LC128/24FC128

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

Name	8-pin PDIP	8-pin SOIC	8-pin TSSOP	8-pin MSOP	8-pin DFN	8-pin CS	Function
A0	1	1	1	—	1	3	User Configurable Chip Select
A1	2	2	2	—	2	2	User Configurable Chip Select
(NC)	—	—	—	1, 2	—	—	Not Connected
A2	3	3	3	3	3	5	User Configurable Chip Select
Vss	4	4	4	4	4	8	Ground
SDA	5	5	5	5	5	6	Serial Data
SCL	6	6	6	6	6	7	Serial Clock
WP	7	7	7	7	7	4	Write-Protect Input
Vcc	8	8	8	8	8	1	+1.7V to 5.5V (24AA128) +2.5V to 5.5V (24LC128) +1.7V to 5.5V (24FC128)

2.1 A0, A1, A2 Chip Address Inputs

The A0, A1 and A2 inputs are used by the 24XX128 for multiple device operations. The levels on these inputs are compared with the corresponding bits in the slave address. The chip is selected if the compare is true.

For the MSOP package only, pins A0 and A1 are not connected.

Up to eight devices (two for the MSOP package) may be connected to the same bus by using different Chip Select bit combinations. These inputs must be connected to either Vcc or Vss.

In most applications, the chip address inputs A0, A1 and A2 are hard-wired to logic '0' or logic '1'. For applications in which these pins are controlled by a microcontroller or other programmable device, the chip address pins must be driven to logic '0' or logic '1' before normal device operation can proceed.

2.2 Serial Data (SDA)

This is a bidirectional pin used to transfer addresses and data into and out of the device. It is an open drain terminal. Therefore, the SDA bus requires a pull-up resistor to Vcc (typical 10 k Ω for 100 kHz, 2 k Ω for 400 kHz and 1 MHz).

For normal data transfer, SDA is allowed to change only during SCL low. Changes during SCL high are reserved for indicating the Start and Stop conditions.

2.3 Serial Clock (SCL)

This input is used to synchronize the data transfer to and from the device.

2.4 Write-Protect (WP)

This pin must be connected to either Vss or Vcc. If tied to Vss, write operations are enabled. If tied to Vcc, write operations are inhibited but read operations are not affected.

3.0 FUNCTIONAL DESCRIPTION

The 24XX128 supports a bidirectional 2-wire bus and data transmission protocol. A device that sends data onto the bus is defined as a transmitter and a device receiving data as a receiver. The bus must be controlled by a master device which generates the Serial Clock (SCL), controls the bus access and generates the Start and Stop conditions while the 24XX128 works as a slave. Both master and slave can operate as a transmitter or receiver, but the master device determines which mode is activated.

24AA128/24LC128/24FC128

4.0 BUS CHARACTERISTICS

The following **bus protocol** has been defined:

- Data transfer may be initiated only when the bus is not busy.
- During data transfer, the data line must remain stable whenever the clock line is high. Changes in the data line while the clock line is high will be interpreted as a Start or Stop condition.

Accordingly, the following bus conditions have been defined (Figure 4-1).

4.1 Bus Not Busy (A)

Both data and clock lines remain high.

4.2 Start Data Transfer (B)

A high-to-low transition of the SDA line while the clock (SCL) is high determines a Start condition. All commands must be preceded by a Start condition.

4.3 Stop Data Transfer (C)

A low-to-high transition of the SDA line, while the clock (SCL) is high, determines a Stop condition. All operations must end with a Stop condition.

4.4 Data Valid (D)

The state of the data line represents valid data when, after a Start condition, the data line is stable for the duration of the high period of the clock signal.

The data on the line must be changed during the low period of the clock signal. There is one bit of data per clock pulse.

Each data transfer is initiated with a Start condition and terminated with a Stop condition. The number of the data bytes transferred between the Start and Stop conditions is determined by the master device.

4.5 Acknowledge

Each receiving device, when addressed, is obliged to generate an Acknowledge signal after the reception of each byte. The master device must generate an extra clock pulse, which is associated with this Acknowledge bit.

Note: The 24XX128 does not generate any Acknowledge bits if an internal programming cycle is in progress.

A device that acknowledges must pull down the SDA line during the acknowledge clock pulse in such a way that the SDA line is stable low during the high period of the acknowledge related clock pulse. Of course, setup and hold times must be taken into account. During reads, a master must signal an end of data to the slave by NOT generating an Acknowledge bit on the last byte that has been clocked out of the slave. In this case, the slave (24XX128) will leave the data line high to enable the master to generate the Stop condition.

FIGURE 4-1: DATA TRANSFER SEQUENCE ON THE SERIAL BUS

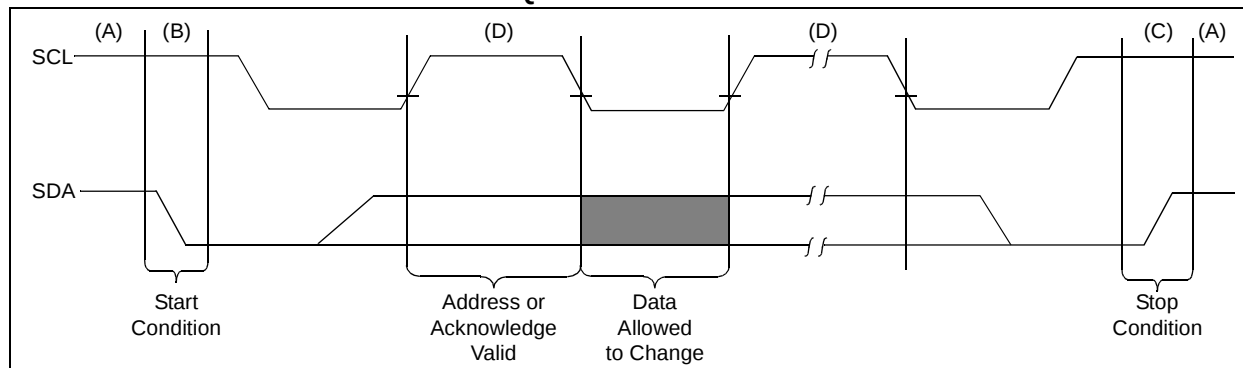
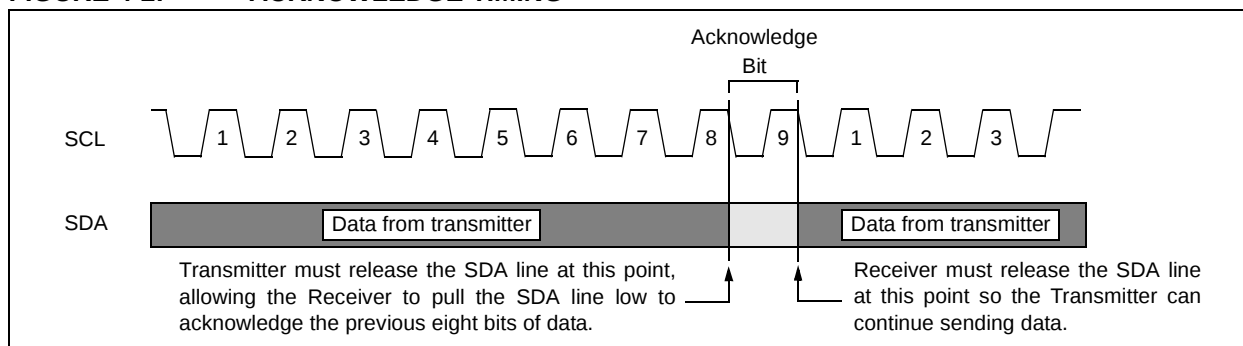


FIGURE 4-2: ACKNOWLEDGE TIMING



5.0 DEVICE ADDRESSING

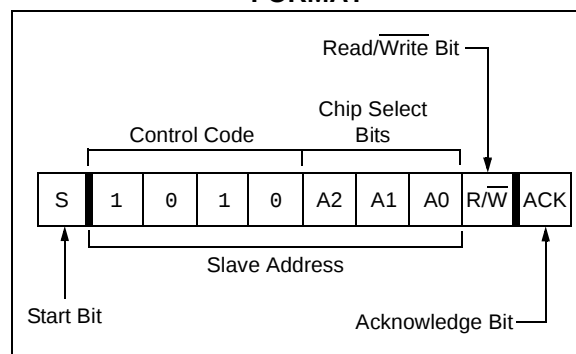
A control byte is the first byte received following the Start condition from the master device (Figure 5-1). The control byte consists of a 4-bit control code. For the 24XX128, this is set as '1010' binary for read and write operations. The next three bits of the control byte are the Chip Select bits (A2, A1, A0). The Chip Select bits allow the use of up to eight 24XX128 devices on the same bus and are used to select which device is accessed. The Chip Select bits in the control byte must correspond to the logic levels on the corresponding A2, A1 and A0 pins for the device to respond. These bits are, in effect, the three Most Significant bits of the word address.

For the MSOP package, the A0 and A1 pins are not connected. During device addressing, the A0 and A1 Chip Select bits (Figures 5-1 and 5-2) should be set to '0'. Only two 24XX128 MSOP packages can be connected to the same bus.

The last bit of the control byte defines the operation to be performed. When set to a one, a read operation is selected. When set to a zero, a write operation is selected. The next two bytes received define the address of the first data byte (Figure 5-2). Because only A13...A0 are used, the upper two address bits are "don't care" bits. The upper address bits are transferred first, followed by the Less Significant bits.

Following the Start condition, the 24XX128 monitors the SDA bus checking the device type identifier being transmitted. Upon receiving a '1010' code and appropriate device select bits, the slave device outputs an Acknowledge signal on the SDA line. Depending on the state of the R/W bit, the 24XX128 will select a read or write operation.

FIGURE 5-1: CONTROL BYTE FORMAT

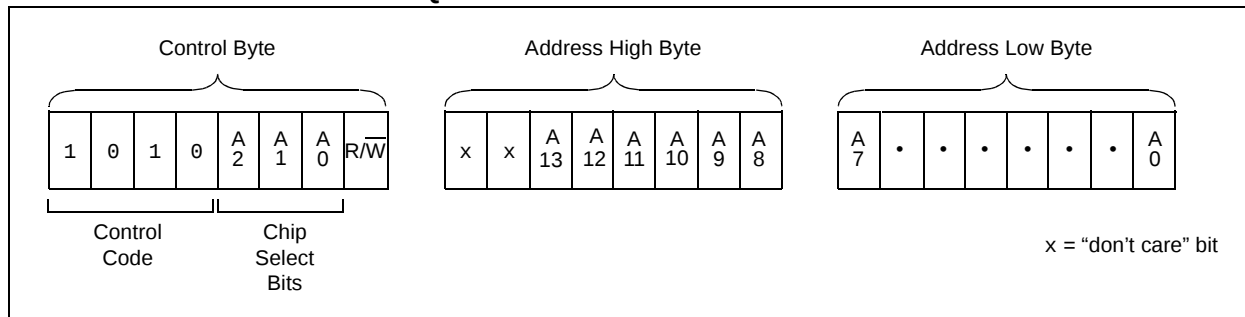


5.1 Contiguous Addressing Across Multiple Devices

The Chip Select bits A2, A1 and A0 can be used to expand the contiguous address space for up to 1 Mbit by adding up to eight 24XX128 devices on the same bus. In this case, software can use A0 of the **control byte** as address bit A14; A1 as address bit A15; and A2 as address bit A16. It is not possible to sequentially read across device boundaries.

For the MSOP package, up to two 24XX128 devices can be added for up to 256 Kbit of address space. In this case, software can use A2 of the control byte as address bit A16. Bits A0 (A14) and A1 (A15) of the **control byte** must always be set to logic '0' for the MSOP.

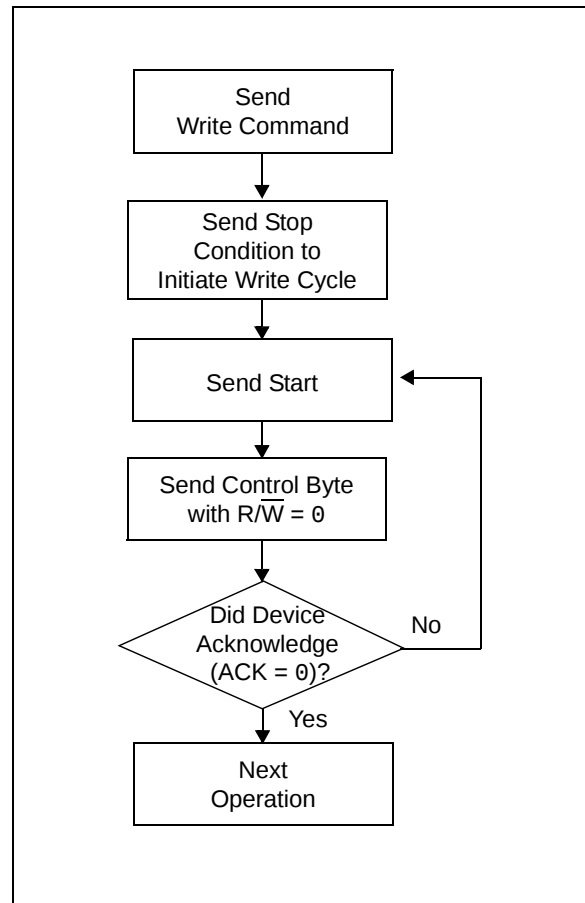
FIGURE 5-2: ADDRESS SEQUENCE BIT ASSIGNMENTS



7.0 ACKNOWLEDGE POLLING

Since the device will not acknowledge during a write cycle, this can be used to determine when the cycle is complete (This feature can be used to maximize bus throughput). Once the Stop condition for a Write command has been issued from the master, the device initiates the internally timed write cycle. ACK polling can be initiated immediately. This involves the master sending a Start condition, followed by the control byte for a Write command ($R/\overline{W} = 0$). If the device is still busy with the write cycle, then no ACK will be returned. If no ACK is returned, the Start bit and control byte must be resent. If the cycle is complete, then the device will return the ACK and the master can then proceed with the next Read or Write command. See Figure 7-1 for flow diagram.

FIGURE 7-1: ACKNOWLEDGE POLLING FLOW



24AA128/24LC128/24FC128

8.0 READ OPERATION

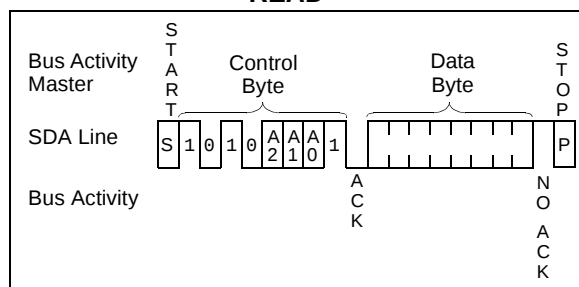
Read operations are initiated in much the same way as write operations with the exception that the $R/\overline{W}$ bit of the control byte is set to '1'. There are three basic types of read operations: current address read, random read and sequential read.

8.1 Current Address Read

The 24XX128 contains an address counter that maintains the address of the last word accessed, internally incremented by '1'. Therefore, if the previous read access was to address 'n' (n is any legal address), the next current address read operation would access data from address $n + 1$.

Upon receipt of the control byte with $R/\overline{W}$ bit set to '1', the 24XX128 issues an acknowledge and transmits the 8-bit data word. The master will not acknowledge the transfer, but does generate a Stop condition and the 24XX128 discontinues transmission (Figure 8-1).

FIGURE 8-1: CURRENT ADDRESS READ



8.2 Random Read

Random read operations allow the master to access any memory location in a random manner. To perform this type of read operation, the word address must first be set. This is done by sending the word address to the 24XX128 as part of a write operation ($R/\overline{W}$ bit set to '0'). Once the word address is sent, the master generates a Start condition following the acknowledge. This terminates the write operation, but not before the internal Address Pointer is set. The master then issues the control byte again, but with the $R/\overline{W}$ bit set to a '1'. The 24XX128 will then issue an acknowledge and transmit the 8-bit data word. The master will not acknowledge the transfer but does generate a Stop condition, which causes the 24XX128 to discontinue transmission (Figure 8-2). After a random Read command, the internal address counter will point to the address location following the one that was just read.

8.3 Sequential Read

Sequential reads are initiated in the same way as a random read except that after the 24XX128 transmits the first data byte, the master issues an acknowledge as opposed to the Stop condition used in a random read. This acknowledge directs the 24XX128 to transmit the next sequentially addressed 8-bit word (Figure 8-3). Following the final byte transmitted to the master, the master will NOT generate an acknowledge but will generate a Stop condition. To provide sequential reads, the 24XX128 contains an internal Address Pointer which is incremented by one at the completion of each operation. This Address Pointer allows the entire memory contents to be serially read during one operation. The internal Address Pointer will automatically roll over from address 3FFF to address 0000 if the master acknowledges the byte received from the array address 3FFF.

FIGURE 8-2: RANDOM READ

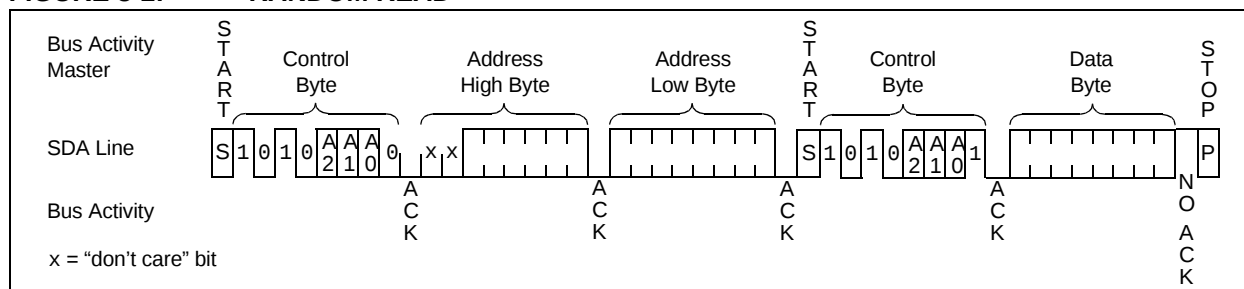
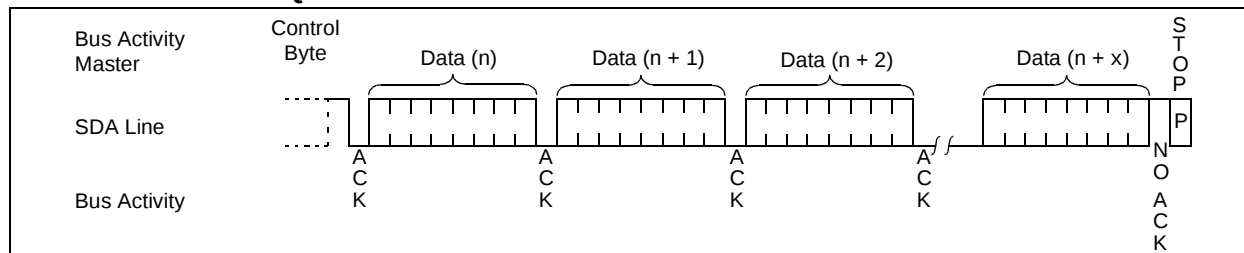


FIGURE 8-3: SEQUENTIAL READ

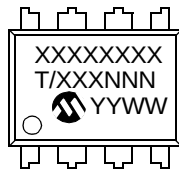


24AA128/24LC128/24FC128

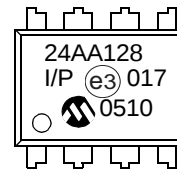
9.0 PACKAGING INFORMATION

9.1 Package Marking Information

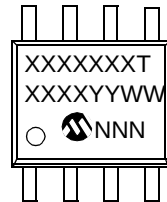
8-Lead PDIP (300 mil)



Example:



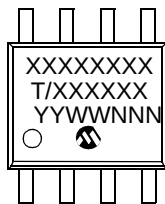
8-Lead SOIC (3.90 mm)



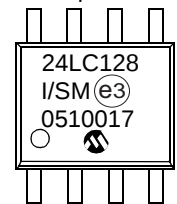
Example:



8-Lead SOIC (5.28 mm)



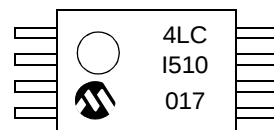
Example:



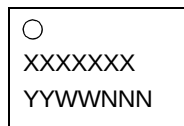
8-Lead TSSOP



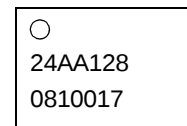
Example:



8-Lead Chip Scale



Example:



24AA128/24LC128/24FC128

Package Marking Information (Continued)

8-Lead MSOP



Example:



8-Lead DFN-S



Example:



Legend:	XX...X	Part number or part number code
	T	Temperature (I, E)
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code (2 characters for small packages)
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)

Note: For very small packages with no room for the Pb-free JEDEC designator (e3), the marking will only appear on the outer carton or reel label.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

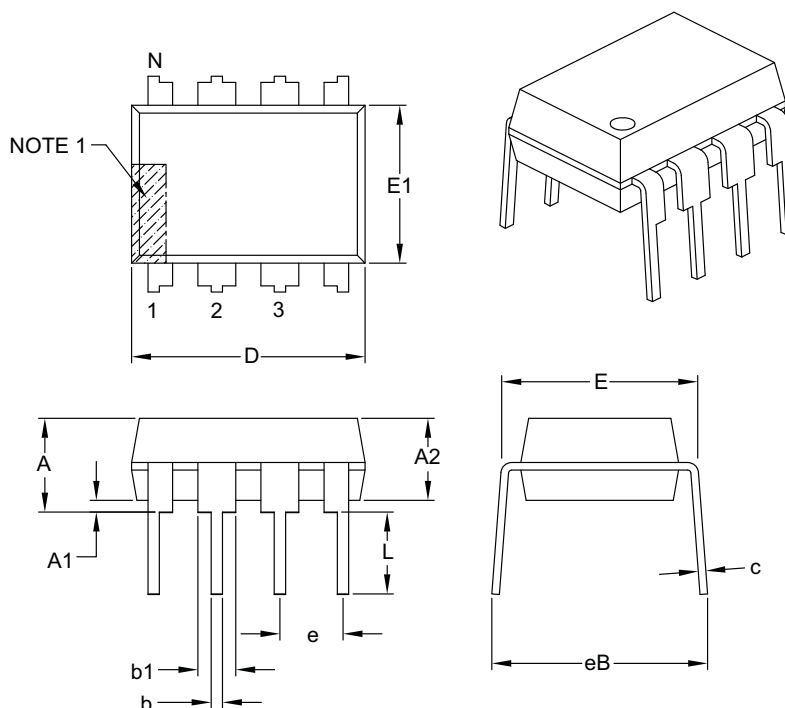
*Standard device marking consists of Microchip part number, year code, week code, and traceability code. For device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office.

Part No.	First Line Marking Codes	
	TSSOP Package Codes	MSOP Package Codes
24AA128	4AC	4A128T
24LC128	4LC	4L128T
24FC128	4FC	4F128T

24AA128/24LC128/24FC128

8-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.348	.365	.400
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

- Pin 1 visual index feature may vary, but must be located with the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- Dimensioning and tolerancing per ASME Y14.5M.

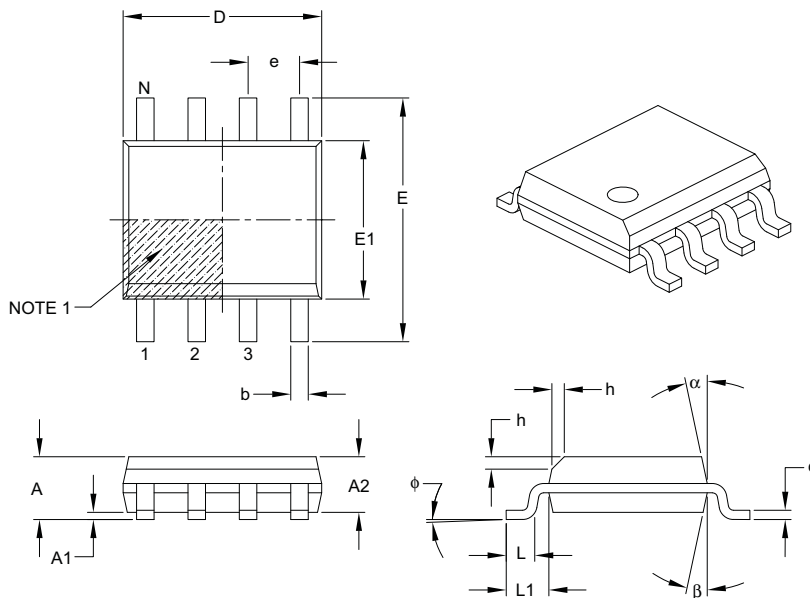
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-018B

24AA128/24LC128/24FC128

8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		8		
Pitch	e		1.27 BSC		
Overall Height	A		–	–	1.75
Molded Package Thickness	A2		1.25	–	–
Standoff §	A1		0.10	–	0.25
Overall Width	E		6.00 BSC		
Molded Package Width	E1		3.90 BSC		
Overall Length	D		4.90 BSC		
Chamfer (optional)	h		0.25	–	0.50
Foot Length	L		0.40	–	1.27
Footprint	L1		1.04 REF		
Foot Angle	φ		0°	–	8°
Lead Thickness	c		0.17	–	0.25
Lead Width	b		0.31	–	0.51
Mold Draft Angle Top	α		5°	–	15°
Mold Draft Angle Bottom	β		5°	–	15°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

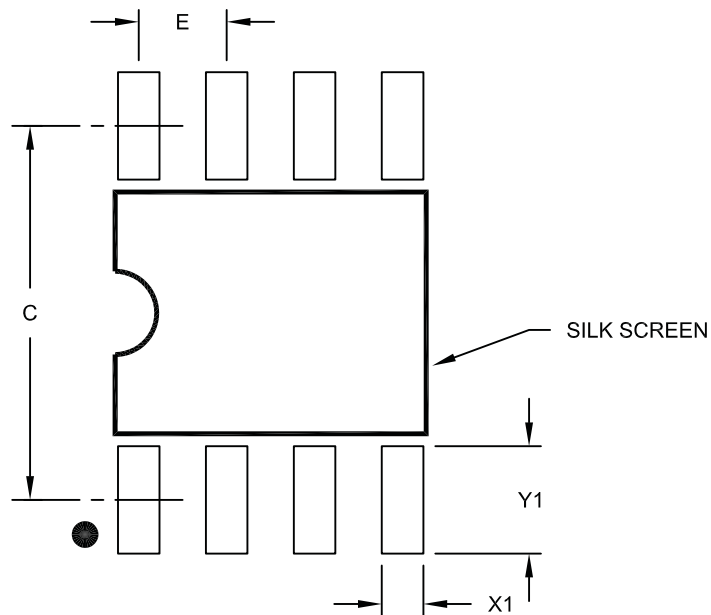
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-057B

24AA128/24LC128/24FC128

8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

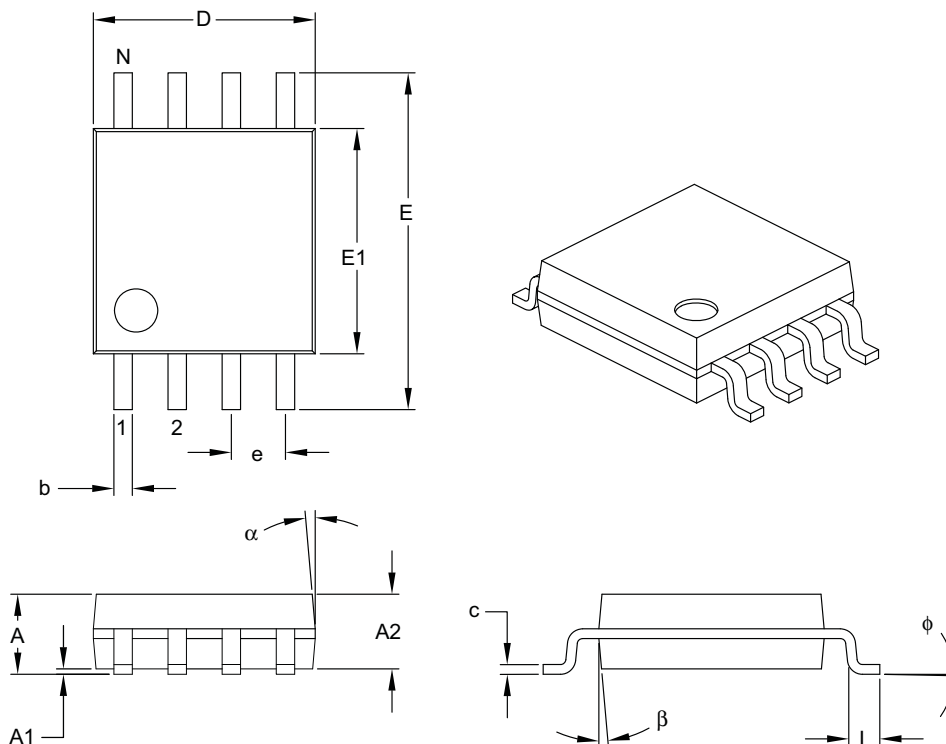
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A

24AA128/24LC128/24FC128

8-Lead Plastic Small Outline (SM) – Medium, 5.28 mm Body [SOIJ]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		8		
Pitch	e		1.27 BSC		
Overall Height	A		1.77	–	2.03
Molded Package Thickness	A2		1.75	–	1.98
Standoff §	A1		0.05	–	0.25
Overall Width	E		7.62	–	8.26
Molded Package Width	E1		5.11	–	5.38
Overall Length	D		5.13	–	5.33
Foot Length	L		0.51	–	0.76
Foot Angle	φ		0°	–	8°
Lead Thickness	c		0.15	–	0.25
Lead Width	b		0.36	–	0.51
Mold Draft Angle Top	α		–	–	15°
Mold Draft Angle Bottom	β		–	–	15°

Notes:

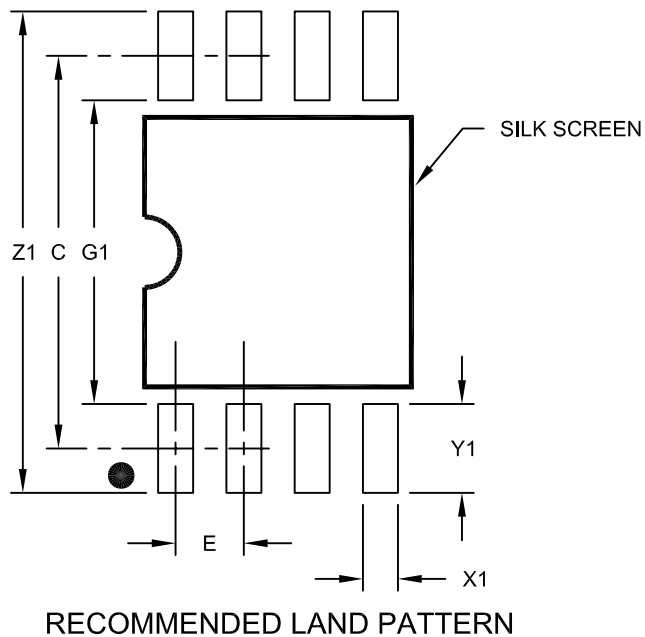
1. SOIJ, JEITA/EIAJ Standard, formerly called SOIC.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.

Microchip Technology Drawing C04-056B

24AA128/24LC128/24FC128

8-Lead Plastic Small Outline (SM) - Medium, 5.28 mm Body [SOIJ]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Overall Width	Z1			9.00
Contact Pad Spacing	C1		7.30	
Contact Pad Width (X28)	X1			0.65
Contact Pad Length (X28)	Y1			1.70
Distance Between Pads	G1	5.60		
Distance Between Pads	G	0.62		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

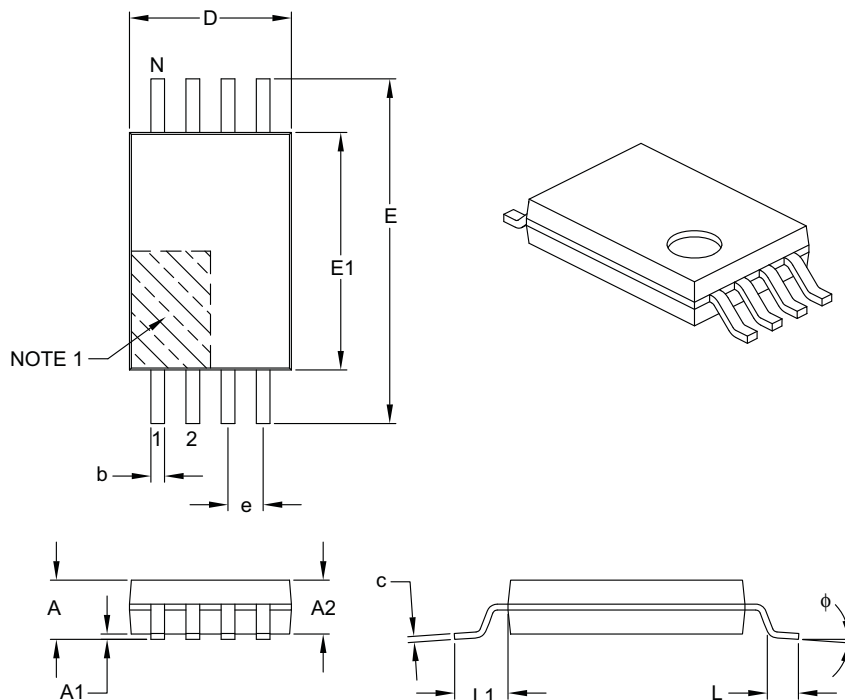
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2056B

24AA128/24LC128/24FC128

8-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.80	1.00	1.05
Standoff	A1	0.05	–	0.15
Overall Width	E	6.40 BSC		
Molded Package Width	E1	4.30	4.40	4.50
Molded Package Length	D	2.90	3.00	3.10
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	ϕ	0°	–	8°
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.19	–	0.30

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

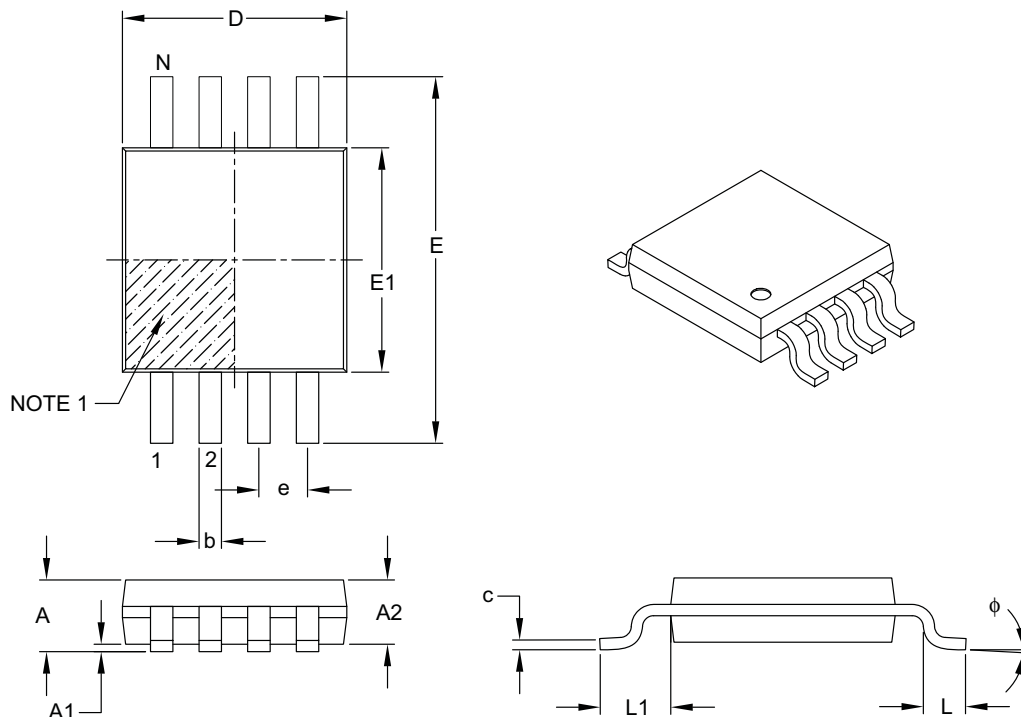
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-086B

24AA128/24LC128/24FC128

8-Lead Plastic Micro Small Outline Package (MS) [MSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	0.65 BSC		
Overall Height	A	—	—	1.10
Molded Package Thickness	A2	0.75	0.85	0.95
Standoff	A1	0.00	—	0.15
Overall Width	E	4.90 BSC		
Molded Package Width	E1	3.00 BSC		
Overall Length	D	3.00 BSC		
Foot Length	L	0.40	0.60	0.80
Footprint	L1	0.95 REF		
Foot Angle	φ	0°	—	8°
Lead Thickness	c	0.08	—	0.23
Lead Width	b	0.22	—	0.40

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

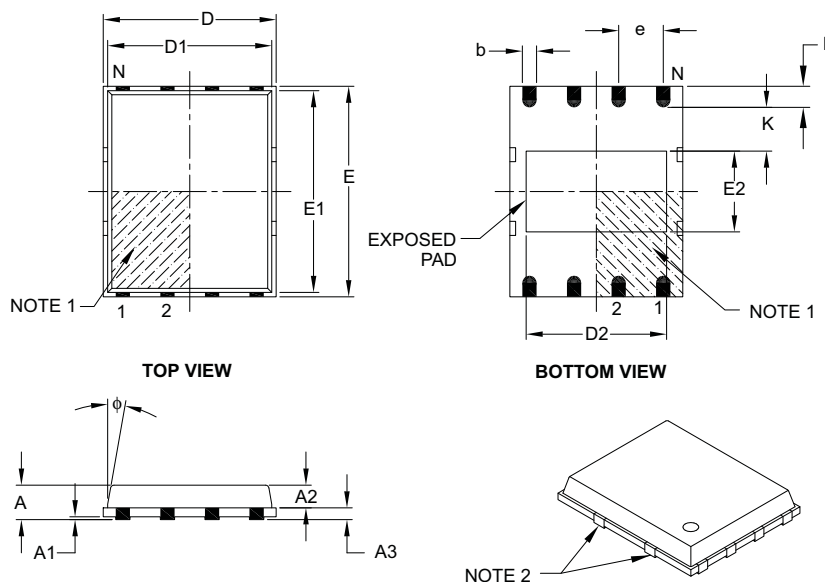
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-111B

24AA128/24LC128/24FC128

8-Lead Plastic Dual Flat, No Lead Package (MF) – 6x5 mm Body [DFN-S] PUNCH SINGULATED

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	–	0.85	1.00
Molded Package Thickness	A2	–	0.65	0.80
Standoff	A1	0.00	0.01	0.05
Base Thickness	A3	0.20 REF		
Overall Length	D	4.92 BSC		
Molded Package Length	D1	4.67 BSC		
Exposed Pad Length	D2	3.85	4.00	4.15
Overall Width	E	5.99 BSC		
Molded Package Width	E1	5.74 BSC		
Exposed Pad Width	E2	2.16	2.31	2.46
Contact Width	b	0.35	0.40	0.47
Contact Length	L	0.50	0.60	0.75
Contact-to-Exposed Pad	K	0.20	–	–
Model Draft Angle Top	φ	–	–	12°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package may have one or more exposed tie bars at ends.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

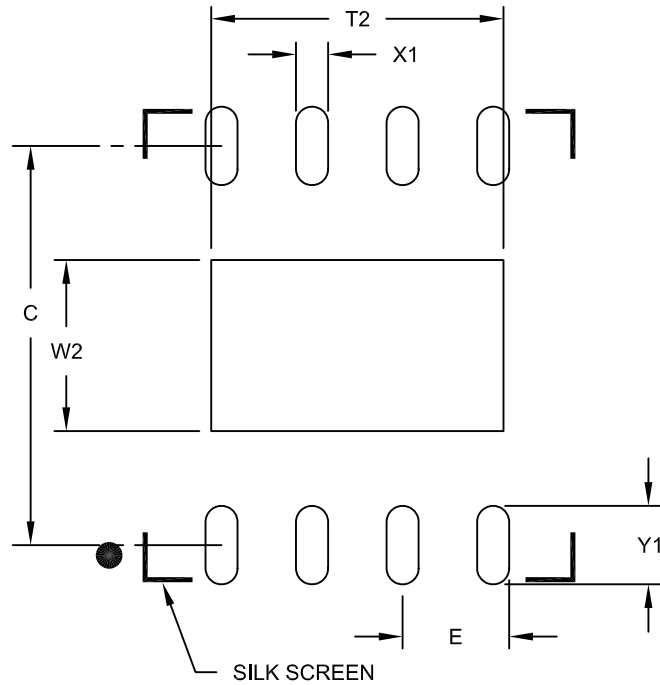
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-113B

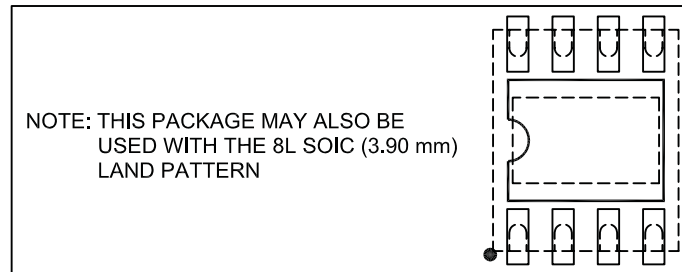
24AA128/24LC128/24FC128

8-Lead Plastic Dual Flat, No Lead Package (MF) - 6x5 mm Body [DFN-S]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Optional Center Pad Width	W2			2.40
Optional Center Pad Length	T2			4.10
Contact Pad Spacing	C		5.60	
Contact Pad Width (X8)	X1			0.45
Contact Pad Length (X8)	Y1			1.10

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

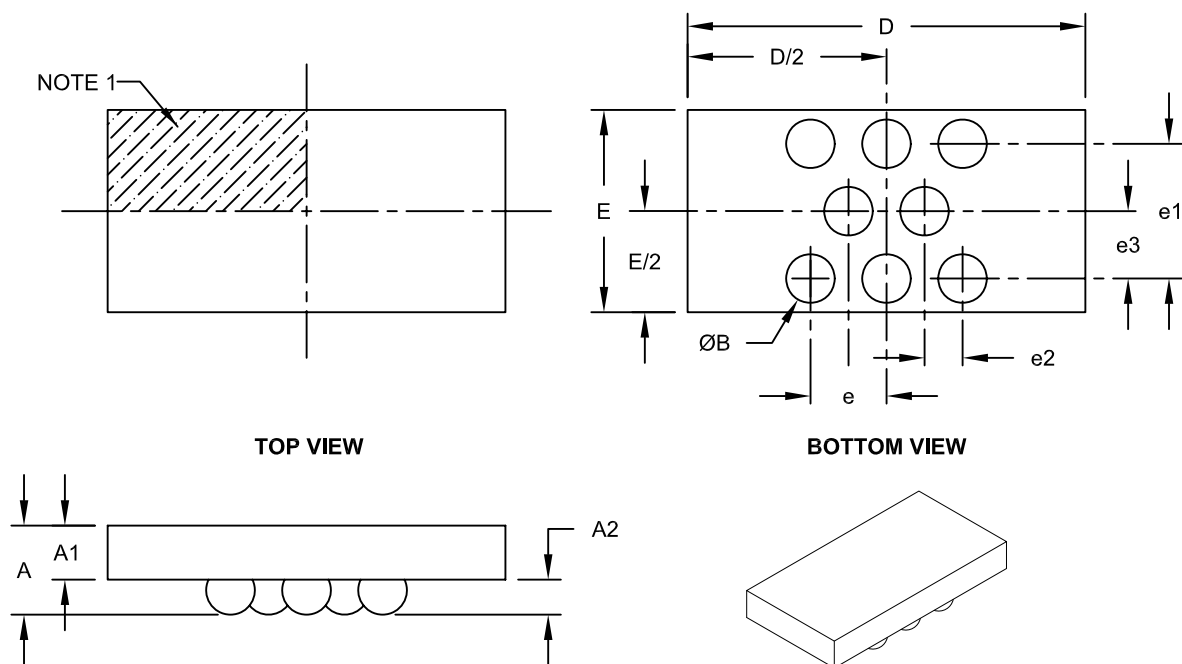
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2122A

24AA128/24LC128/24FC128

8-Lead Chip Scale Package (CS) – 3x2x3 Ball Pattern [CSP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Contacts	N		8	
X-Pitch	e		0.50	
Overall Grid Y-Pitch	e1		0.886	
Adjacent Column X-Pitch	e2		0.25	
Adjacent Row Y-Pitch	e3		0.443	
Overall Height	A	0.535	0.585	0.635
Encapsulated Package Height	A1	0.330	0.355	0.380
Contact Thickness	A2	0.205	0.230	0.255
Overall Width	E	NOTE 4		
Edge to Center of Array	E/2	NOTE 4		
Overall Length	D	NOTE 4		
Edge to Center of Array	D/2	NOTE 4		
Contact Diameter	B	0.29	0.32	0.35

Notes:

- Orientation reference feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.
- Package size varies with specific devices. Please contact your local Microchip representative for specific details.

Microchip Technology Drawing C04-145A

APPENDIX A: REVISION HISTORY

Revision L

Corrections to Section 1.0, Electrical Characteristics.

Revision M

Added 1.8V 400 kHz option for 24FC128.

Revision N

Revised Sections 2.1, 2.4 and 6.3. Removed 14-Lead TSSOP Package.

Revision P

Changed 1.8V to 1.7V throughout document; Revised Features Section; Replaced Package Drawings; Revised Product ID Section.

Revision Q (June 2008)

Updated packaging; Added Chip Scale package.

24AA128/24LC128/24FC128

NOTES:

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24AA128/24LC128/24FC128

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2. How does this document meet your hardware and software development needs?

3. Do you find the organization of this document easy to follow? If not, why?

4. What additions to the document do you think would enhance the structure and subject?

5. What deletions from the document could be made without affecting the overall usefulness?

6. Is there any incorrect or misleading information (what and where)?

7. How would you improve this document?

24AA128/24LC128/24FC128

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>X</u>	<u>XX</u>
Device	Temperature Range	Package
Device: 24AA128: 128 Kbit 1.7V I²C Serial EEPROM 24AA128T: 128 Kbit 1.7V I²C Serial EEPROM (Tape and Reel) 24LC128: 128 Kbit 2.5V I²C Serial EEPROM 24LC128T: 128 Kbit 2.5V I²C Serial EEPROM (Tape and Reel) 24FC128: 128 Kbit High Speed I²C Serial EEPROM 24FC128T: 128 Kbit High Speed I²C Serial EEPROM (Tape and Reel)		
Temperature Range: - I = -40°C to +85°C - E = -40°C to +125°C		
Package: - P = Plastic DIP (300 mil body), 8-lead - SN = Plastic SOIC (3.90 mm body), 8-lead - SM = Plastic SOIC (5.28 mm body), 8-lead - ST = Plastic TSSOP (4.4 mm), 8-lead - MF = Dual, Flat, No Lead (DFN) (6x5 mm body), 8-lead - MS = Plastic Micro Small Outline (MSOP), 8-lead - CS15K⁽¹⁾ = Chip Scale (CS), 8-lead (I-temp, "AA", Tape and Reel only)		
Note 1: "15K" indicates 150K technology		
Examples: a) 24AA128-I/P: Industrial Temp., 1.7V, PDIP package. b) 24AA128T-I/SN: Tape and Reel, Industrial Temp., 1.7V, SOIC package. c) 24AA128-I/ST: Industrial Temp., 1.7V, TSSOP package. d) 24AA128-I/MS: Industrial Temp., 1.7V, MSOP package. e) 24LC128-E/P: Extended Temp., 2.5V, PDIP package. f) 24LC128-I/SN: Industrial Temp., 2.5V, SOIC package. g) 24LC128T-I/SN: Tape and Reel, Industrial Temp., 2.5V, SOIC package. h) 24LC128-I/MS: Industrial Temp., 2.5V, MSOP package. i) 24FC128-I/P: Industrial Temp., 1.7V, High Speed, PDIP package. j) 24FC128-I/SN: Industrial Temp., 1.7V, High Speed, SOIC package. k) 24FC128T-I/SN: Tape and Reel, Industrial Temp., 1.7V, High Speed, SOIC package l) 24AA128T-I/CS15K: Industrial Temp., 1.7V, CS package, Tape and Reel		

24AA128/24LC128/24FC128

NOTES:

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